| PCN Number: | er: 20150625001 | | | | | PCN Date: 07/2 | 0/2015 |
|--|---|-------|-------------------|----------|-------------------|-----------------------|--------|
| Title: Datasheet up | date for BQ2 | 2589 | 90/BQ25892 | | | • | |
| Customer Contact: | PCN Manage | | Dept: | Quality | Ser | vices | |
| Proposed 1 st Ship Da | | | | , , | | | |
| Change Type: | | , | | | | | |
| Assembly Site | | | Design | | П | Wafer Bump Site | |
| Assembly Process | | | Data Sheet | | Ħ | Wafer Bump Mate | erial |
| Assembly Material | S | Ï | Part number char | nge | П | Wafer Bump Proc | |
| Mechanical Specification | | | Test Site | J | 靣 | Wafer Fab Site | |
| Packing/Shipping/Labeling | | | Test Process | | $\overline{\Box}$ | Wafer Fab Materi | als |
| | | | | | | Wafer Fab Proces | S |
| PCN Details | | | | | | | |
| Description of Chang | e: | | | | | | |
| The product datasheet(| | ıpda | ated as summarize | d below. | | | |
| • | | • | | | | | |
| The following change h | istory provid | les ' | further details: | | | | |
| | | | | | | | |
| | | | | | | | |
| | | | | | | Mar on | |
| | | | | | | TEXAS INSTRUM | ENTS |
| bq25890, bq25892 | | | | | | - INSTRUM | ENIS |
| SLUSBU7A - MARCH 2015-REVISED | JUNE 2015 | | | | | www. | ti.com |
| Changes from Revision Marc | ch (2015) to Rev | ision | Α | | | | Page |
| Added "Technology" to the | data sheet title | | | | | | 1 |
| | | | | | | | |
| | Deleted text form the OTG pin Description "OTG = High, IINLIM is set to USB500 mode" | | | | | | |
| | Changed V _(SLEEPZ) and V _(SLEEPZ) Unit From: V To: mV | | | | | | |
| | Added TYP values to I _{IN(DPM_ACC)} in the <i>Electrical Characteristics</i> table9 | | | | | | |
| Deleted D+/D- DETECTION (bq25890) from the <i>Timing Requirements</i> 13 | | | | | | | |
| | Added condition "DCR = 10 mΩ" to Figure 1 | | | | | | |
| | Deleted V _{CHG_REG} and I _{BAT_REG} at Q4 gate Control in the <i>Functional Block Diagram</i> | | | | | | |
| Deleted "SDP STAT bit is updated to indicate USB100 or other input source" from <i>Input Source Type Detection</i> | | | | | | | |
| Changed Figure 9, SDP(USB100/USB500) To: SDP (USB500) | | | | | | | |
| Deleted USB SDP (USB100) and the OTG Pin column from Table 3 and Table 4 | | | | | | | |
| Added text to the PSEL/OTG Pins Set Input Current Limit (bq25892) section: "To implement USB100 in the system" 19 | | | | | | | |
| Deleted section: Plug in USB100 Source | | | | | | | |
| Added text to Input Voltage Limit Threshold Setting (VINDPM Threshold), "After Input Voltage Limit Threshold" 20 | | | | | | | |
| Changed text in Input Current Optimizer (ICO) From: "After DCP type" To: "After DCP or MaxCharge type" | | | | | | | |
| Changed Equation 1, From: BATCOMP, VREG + V _{CLAMP} To: BATCOMP, V _{CLAMP} | | | | | | | |
| Changed the Description of the INLIM Bits in Table 9 | | | | | | | |
| Changed Table 14, Bits 3 to 0, From: Default: 128mA (0011) To: Default: 256mA (0011) | | | | | | | |
| Changed Bit 1 From: SDP_STAT To: Reserved | | | | | | | |
| Changed V _{IN} To: V _{BUS} in Equation 6 | | | | | | | |
| Changed Input Capacitor T | Changed Input Capacitor To: Buck Input Capacitor | | | | | | |
| Changed I_{CIN} to I_{PMID} in But | Changed I _{CIN} to I _{PMID} in <i>Buck Input Capacitor</i> and Equation 7 | | | | | 52 | |
| Changed "15-V input voltage | • Changed "15-V input voltage. 22-µF capacitanc" To: "14-V input voltage. 8.2-µF capacitance" in <i>Buck Input Capacitor</i> 52 | | | | | | |
| Changed Output Capacitor To: System Output Capacitor | | | | | | | |
| Changed I _{COUT} To: I _{CSYS} in Equation 8 , Changed Equation 9 | | | | | | | |
| | | | | | | | |
| | | | | | | | |
| | | | | | | | |

The datasheet number will be changing.

| Device Family | Change From: | Change To: |
|-----------------|-----------------|-------------------|
| bq25890/bq25892 | SLUSC86/SLUSBU7 | SLUSC86A/SLUSBU7A |

These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/bq25890

Special note

For Full Data Sheet and User Guide, click here.

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

To more accurately reflect device characteristics.

Changes to product identification resulting from this PCN:

None.

Product Affected:

| | BQ25890RTWR | BQ25890RTWT | BQ25892RTWR | BQ25892RTWT |
|--|-------------|-------------|-------------|-------------|
|--|-------------|-------------|-------------|-------------|

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

| Location | E-Mail |
|--------------|--------------------------------|
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| Europe | PCNEuropeContact@list.ti.com |
| Asia Pacific | PCNAsiaContact@list.ti.com |
| Japan | PCNJapanContact@list.ti.com |